

ABSTRACT

The present invention is a laser processing apparatus for performing laser processing by irradiating a substrate arranged on a substrate stage with laser light, the laser processing apparatus comprising: a laser device that oscillates the laser light; a reduced projection optical system; and the substrate stage, and the laser processing apparatus includes a shutter between the reduced projection optical system and the substrate stage. Accordingly, a laser processing apparatus capable of suppressing influence of dimensional change of the reduced projection optical system caused by temperature change of the reduced projection optical system and suppressing a decrease in throughput of the laser processing can be provided.